

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHIN-WEN YEY	09/08/2007
ZHEN-NENG LIN	09/08/2007
RECEIVING PARTY DATA	
Name:	HONG FU JIN PRECISION INDUSTRY (ShenZhen) CO., LTD.
Street Address:	No. 2, 2nd Donghuan Road, Longhua Town, Bao' an District
City:	Shenzhen City, Guangdong Province
State/Country:	CHINA
Name:	HON HAI PRECISION INDUSTRY CO., LTD.
Street Address:	66, CHUNG SHAN ROAD
City:	Tu-Cheng, Taipei Hsien
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11858133
CORRESPONDENCE DATA	
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<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
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ATTORNEY DOCKET NUMBER:	US16023
NAME OF SUBMITTER:	Frank R. Niranjan

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PATENT
REEL: 019849 FRAME: 0882

Total Attachments: 2

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ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1. Chin-Wen Yeh, residing at Tu-Cheng, Taipei, Taiwan
2. Zhen-Neng Lin, residing at Shenzhen, Guangdong, China
3. _____, residing at _____
4. _____, residing at _____
5. _____, residing at _____
6. _____, residing at _____
7. _____, residing at _____
8. _____, residing at _____

hereby sell(s), assign(s) and transfer(s) unto: HONG FU JIN PRECISION INDUSTRY (ShenZhen) CO., LTD. having a principal place of business at No.2, 2nd Donghuan Road, Longhua Town, Bao'an District, Shenzhen City, Guangdong Province 518109, P.R.C. and HON HAI PRECISION INDUSTRY CO., LTD. having a principal place of business at 66, Chung Shan Road, Tu-Cheng City, Taipei Hsien, Taiwan, R.O.C. hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as VIBRATION DAMPENING STRUCTURE FOR ELECTRONIC DEVICE for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____

[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>Chin-Wen Yeh</u>	<u>2007/09/08</u>	_____
	Chin-Wen Yeh inventor	Date	Witness
2.	<u>Zhen-Neng Lin</u>	<u>2007/09/08</u>	_____
	Zhen-Neng Lin inventor	Date	Witness
3.	_____	_____	_____
	_____ inventor	Date	Witness
4.	_____	_____	_____
	_____ inventor	Date	Witness
5.	_____	_____	_____
	_____ inventor	Date	Witness
6.	_____	_____	_____
	_____ inventor	Date	Witness
7.	_____	_____	_____
	_____ inventor	Date	Witness
8.	_____	_____	_____
	_____ inventor	Date	Witness